Pac Tech achieves ISO 9001 Registration

For the Equipment Manufacturing Facility
Berlin, Germany – September 10, 2001 – Pac Tech GmbH, a leading supplier of services, equipment and Processes for semiconductor wafer bumping, today announced that it has been awarded ISO 9001 registration for Pac Tech GmbH, Berlin, Germany, its Equipment Manufacturing facility, where the following equipment is build:

Solder Ball Placement System: SB2-A & SB2-SM
Ultra High Speed Solder Jetting System: SB2-JET
Laser Flip Chip Bonder: LAPLACE
Automatic Ni/Au Plating Line: PacLine 2000

TÜV granted the certification, whose accreditation is formally recognized throughout the United States, Canada and Europe. Through registration, Pac Tech GmbH joins the ranks of an elite number of International firms registered to the ISO 9001 standard for quality systems within a defined scope of business activities such as documentation, process control, product quality, and reliability.
"The ISO 9001 registration for the Equipment Manufacturing Facility Berlin is a major milestone for us. This demonstrates our on-going commitment to high quality and excellent customer service" said Dr. Elke Zakel, President & CEO. The Wafer Bumping Production facility was already qualified in October 2000.

ISO 9001 certified Production Line for the semiautomatic and automatic Solder Ball Placement System SB^2-SM & SB^2-A

ISO 9001 certified Production Line for electroless Ni/Au-Bumping on Wafer Level- PacLine 2000 A25